

# Z-COAT 122B



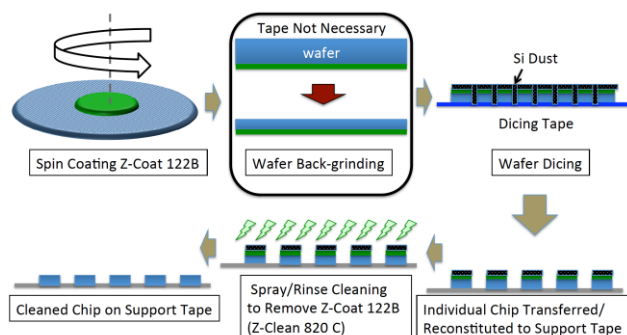
## Water Resist Coating for Wafer Mechanical Sawing Protection

Z-COAT 122B is a spin on liquid polymer coating on wafer front for protection from contamination or Si dust during mechanical sawing. Z-Coat 122B becomes wafer-resist and hard transparent coating after a quick 2 minutes bake at 150 °c. Z-Coat 122B coating can be completely removed with aqueous cleaner Z-Clean 820C spray/soak, followed by Di-water rinse. Carrier debonding with air-jetting (AirDebond®).

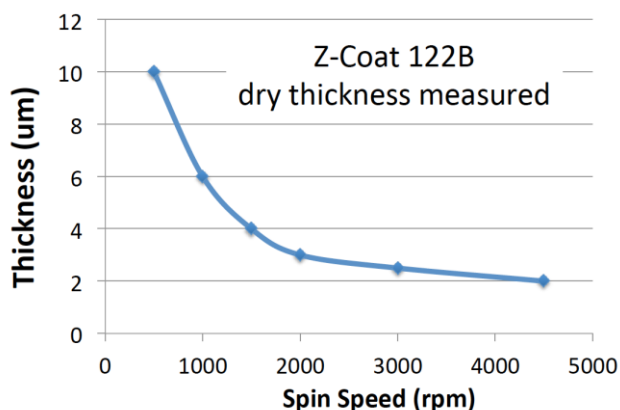
### Basic Material Property:

Z-COAT 122B	
Appearance	Transparent Liquid
Viscosity	60~70 cps
Solvent	DMSO
Coating	Spin Coating or Spray
Hard Bake	150°C for 2 minutes
Tackiness	Tacky-free after hard bake
Cleaning	Environmental Friendly Metal Safe Aqueous Cleaning Solution
Storage	Room Temperature

### Process Flow with Mechanical Sawing:



### Spin Coating:



Recommended thickness is ~ 3 µm (at 1500 ~ 2000 rpm spin speed).

### Hard Bake:

Thickness	Baking Schedule
< 10 µm	150 °C for 2 minutes

Z-Coat 122B quickly turns to solid film after baked at 100 °C for 1 minute. It can be baked a higher temperature than 180 °C for quicker solvent removal.

### Hot Water Soak Test:

NO weight gain after 60 minutes soaking in 90 °C hot water.

### Tape Peel Test:

NO Damage after high sticky tape peel off.

### Dicing Chipping Test:

Less than 5 µm chipping/peeling.

### Cleaning:

Z-Coat 122B coating can be completely removed with spray/soak aqueous cleaner Z-Clean 820 C and Di-water rinse.

### After Cleaning:

Nonhazardous waste may be able to go down the drain.

### Contact:

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